

# CEDA EC Meeting

26 April 2024

# Agenda

- Roll Call
- Approval of April Agenda
- Approval of March Minutes
- Division I Meeting at ISCAS
- Student Travel Grant Requirements
- DAC 2024
  - Conference Update
  - Publicity
- Conference Distinguished Speaker Luncheons
  - DAC
  - ICCAD
- Awards
- Publications
  - ESL Discussion
- DivEDA
- 20th Anniversary
- Admin
  - DAC RSVP
  - CAT2 Website
  - Outstanding Bylaws Updates

# Welcome - Silveira

- Roll Call
- Approval of April Agenda
- Approval of March Minutes

# Division I Meeting at ISCAS - Bolchini

# Student Travel Grant Requirements - Silveira

# DAC Updates

Miguel Silveira

April 26, 2024

# DAC 2024 - Silveira

- Conference Update
- Publicity

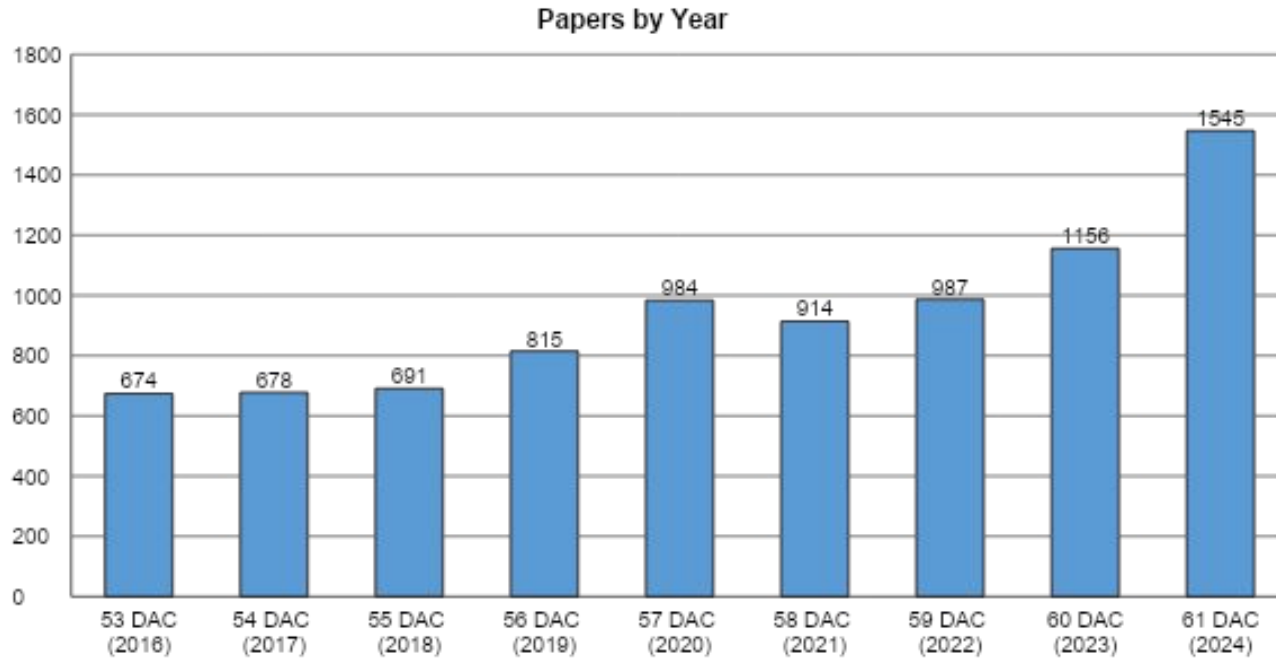
# DAC 2024 - Record number of submissions

**Record number of submissions:** 2079 Abstracts, 1575 PDFs; **1545** final valid submissions after some withdrawing (cf. 1156 in 2023 => **34% increase**)

TPC committee: 29 tracks, 34 track chairs, 356 TPC members (cf. 266 in 2023 => **34% increase**)



# Research Paper Submission History



- 34% increase in submissions!
- Clearly a lot of momentum in the Semiconductor, EDA, AI and Security areas.

# Top tracks/topics in paper attraction

Track	#papers
AI1. AI/ML Algorithms	80
AI2. AI/ML Application and Infrastructure	74
DES3B-I. In-memory and Near-memory Computing Architectures, Applications and Systems - I	58
DES3B-II. In-memory and Near-memory Computing Architectures, Applications and Systems - II	60
DES4-I. AI/ML Architecture Design - I	57
DES4-II. AI/ML Architecture Design - II	53
DES9. Quantum Computing	78
EDA3. Timing and Power Analysis and Optimization	60
EDA5. Analog CAD, Simulation, Verification and Test	54
EDA6. Physical Design and Verification	71
EDA7. Design for Manufacturing and Reliability	51
SEC1. Hardware Security: Primitives, Architecture, Design & Test	63



# Accepted Sessions by Country

- 337 submissions accepted
- 21.8% acceptance rate  
(cf. 22.7% in 2023)
- Most accepted submissions from China and US
  - 153 papers (45%) with a primary author from China
  - 82 papers (24%) from USA



2023

Country	Percentage
China	41.06%
United States	30.42%
Hong Kong	6.46%
Korea	5.70%
Taiwan	4.94%
Germany	3.42%
Switzerland	2.28%
United Kingdom	1.90%
Belgium	0.76%
Italy	0.76%
Austria	0.38%
Canada	0.38%
France	0.38%
Greece	0.38%
Japan	0.38%
Singapore	0.38%

2024

Country	Percentage
China	45.40%
United States	24.33%
Korea	7.12%
Hong Kong	6.82%
Germany	3.56%
Taiwan	2.97%
Italy	1.48%
Singapore	1.19%
Japan	0.89%
United Arab Emirates	0.89%
United Kingdom	0.89%
Austria	0.59%
Canada	0.59%
France	0.59%
Greece	0.59%
Switzerland	0.59%
Belgium	0.30%
India	0.30%
Luxembourg	0.30%
Netherlands	0.30%
Norway	0.30%



# DAC 2024 CEDA Luncheon Keynote - O'Connor

- Scheduled for Tuesday June 25th 12:00pm-1:30pm (PDT)
- Ranked list of 7 names after DATE EC meeting vote (March 24th)
  - Douglas Yu, TSMC - Topic: 3D chiplets and heterogeneous integration
  - Li-Shiuan Peh, NUS (Female) - Topic: Next generation wearables
  - Ingrid Verbauwhede, KU Leuven - Topic: Hardware Security
  - Pieter Abbeel, UCB - Topic: Robotics, reinforcement learning
  - Jelena Vuckovic, Stanford - Topic: Photonics
  - Andrew Kahng, UCSD - Topic: Open-Source EDA
  - Diana Marculescu, UT Austin - Topic: On-device learning

# Followup and outcome

- Invited names on ranked list
  - April 2<sup>nd</sup> Douglas Yu, TSMC – schedule conflict
  - April 9<sup>th</sup> Li-Shiuan Peh, NUS (Female) – on vacation
  - April 10<sup>th</sup> Pieter Abbeel, UCB – overbooked
  - April 13<sup>th</sup> Ingrid Verbauwhede, KU Leuven – exam period in Leuven
  - April 15<sup>th</sup> Jelena Vuckovic, Stanford – giving a talk at another event
  - April 20<sup>th</sup> Andrew Kahng, UCSD – accepted! Will communicate topic/title to converge
- Next year – start the process earlier

# ICCAD 2024 CEDA Luncheon Keynote

- Scheduled for Tuesday October 29th 1pm-2pm (tbc)
- Jiang Hu (CEDA ICCAD representative) proposed list of 3 names:
  - Patrick Groeneveld, AMD Senior Fellow, EDA veteran, former DAC general chair, recently with an AI hardware startup (Cerebras) prior to his AMD position.
  - Subramanian Iyer, Director of the National Advanced Packaging Manufacturing Program, US Department of Commerce, famous in the field of 3D heterogeneous integration, Distinguished Professor at UCLA till last year, also formerly an IBM fellow.
  - Sophia Shao, assistant professor at UC Berkeley. While relatively junior, she is an absolute star. Research related to EDA and mostly on computer architecture, with an emphasis on AI hardware. Received the DAC 21 best paper award, industrial experience at IBM and Nvidia.
- complementarity to ICCAD keynotes already scheduled (Leon Stok, IBM / Philip Wong, Stanford / Dilma Da Silva, US NSF)

# Proposal for selection process

- Until May 13 – all CEDA EC members can suggest alternative suggestions (send name, affiliation and topic keywords to Laura & Ian) and/or contribute to online discussion on candidates via email
- May 14 – set up e-vote (Laura / Ian)
- May 15-23 – all CEDA members participate in e-vote
- May 24 – announcement of ranked list (Ian)
- May 24 onward – invite names on ranked list (Ian)

# Awards - Chen



# Publications - Henkel

- ESL Discussion (possible move to bimonthly publication)

# DivEDA - Silveira

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# CEDA's 20th Anniversary - Gielen

# Administrative - Paul/Osborn

- DAC RSVP - **Friday, 10 May 2024**
- CAT2 Website Updates
- Outstanding Bylaws Updates